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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Not For New Designs
Core Processor	8051
Core Size	8-Bit
Speed	20MHz
Connectivity	SMBus (2-Wire/I ² C), SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, Temp Sensor, WDT
Number of I/O	16
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 3.6V
Data Converters	A/D 8x12b; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-TQFP
Supplier Device Package	48-TQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/c8051f001-gqr

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

1. SYSTEM OVERVIEW

The C8051F000 family are fully integrated mixed-signal System on a Chip MCUs with a true 12-bit multi-channel ADC (F000/01/02/05/06/07), or a true 10-bit multi-channel ADC (F010/11/12/15/16/17). See the Product Selection Guide in Table 1.1 for a quick reference of each MCUs' feature set. Each has a programmable gain pre-amplifier, two 12-bit DACs, two voltage comparators (except for the F002/07/12/17, which have one), a voltage reference, and an 8051-compatible microcontroller core with 32kbytes of FLASH memory. There are also I2C/SMBus, UART, and SPI serial interfaces implemented in hardware (not "bit-banged" in user software) as well as a Programmable Counter/Timer Array (PCA) with five capture/compare modules. There are also 4 general-purpose 16-bit timers and 4 byte-wide general-purpose digital Port I/O. The C8051F000/01/02/10/11/12 have 256 bytes of RAM and execute up to 20MIPS, while the C8051F005/06/07/15/16/17 have 2304 bytes of RAM and execute up to 25MIPS.

With an on-board VDD monitor, WDT, and clock oscillator, the MCUs are truly stand-alone System-on-a-Chip solutions. Each MCU effectively configures and manages the analog and digital peripherals. The FLASH memory can be reprogrammed even in-circuit, providing non-volatile data storage, and also allowing field upgrades of the 8051 firmware. Each MCU can also individually shut down any or all of the peripherals to conserve power.

On-board JTAG debug support allows non-intrusive (uses no on-chip resources), full speed, in-circuit debug using the production MCU installed in the final application. This debug system supports inspection and modification of memory and registers, setting breakpoints, watchpoints, single stepping, and run and halt commands. All analog and digital peripherals are fully functional when using JTAG debug.

Each MCU is specified for 2.7V-to-3.6V operation over the industrial temperature range (-45C to +85C). The Port I/Os, /RST, and JTAG pins are tolerant for input signals up to 5V. The C8051F000/05/10/15 are available in the 64-pin TQFP (see block diagram in Figure 1.1). The C8051F001/06/11/16 are available in the 48-pin TQFP (see block diagram in Figure 1.2). The C8051F002/07/12/17 are available in the 32-pin LQFP (see block diagram in Figure 1.3).

	MIPS (Peak)	FLASH Memory	RAM	SMBus/I2C	IdS	UART	Timers (16-bit)	Programmable Counter Array	Digital Port I/O's	ADC Resolution (bits)	ADC Max Speed (ksps)	ADC Inputs	Voltage Reference	Temperature Sensor	DAC Resolution	DAC Outputs	Voltage Comparators	Package
C8051F000	20	32k	256	\checkmark	\checkmark	\checkmark	4	\checkmark	32	12	100	8	\checkmark	\checkmark	12	2	2	64TQFP
C8051F001	20	32k	256	\checkmark	\checkmark	\checkmark	4	\checkmark	16	12	100	8	\checkmark	\checkmark	12	2	2	48TQFP
C8051F002	20	32k	256	\checkmark	\checkmark	\checkmark	4	\checkmark	8	12	100	4	\checkmark	\checkmark	12	2	1	32LQFP
C8051F005	25	32k	2304		\checkmark	\checkmark	4	\checkmark	32	12	100	8	\checkmark	\checkmark	12	2	2	64TQFP
C8051F006	25	32k	2304		\checkmark	\checkmark	4		16	12	100	8	\checkmark	\checkmark	12	2	2	48TQFP
C8051F007	25	32k	2304		\checkmark	\checkmark	4	\checkmark	8	12	100	4	\checkmark	\checkmark	12	2	1	32LQFP
C8051F010	20	32k	256		\checkmark	\checkmark	4	\checkmark	32	10	100	8	\checkmark	\checkmark	12	2	2	64TQFP
C8051F011	20	32k	256	\checkmark	\checkmark	\checkmark	4	\checkmark	16	10	100	8	\checkmark	\checkmark	12	2	2	48TQFP
C8051F012	20	32k	256				4		8	10	100	4	\checkmark	\checkmark	12	2	1	32LQFP
C8051F015	25	32k	2304		\checkmark	\checkmark	4	\checkmark	32	10	100	8	\checkmark	\checkmark	12	2	2	64TQFP
C8051F016	25	32k	2304		\checkmark	\checkmark	4	\checkmark	16	10	100	8	\checkmark	\checkmark	12	2	2	48TQFP
C8051F017	25	32k	2304		\checkmark	\checkmark	4	\checkmark	8	10	100	4	\checkmark	\checkmark	12	2	1	32LQFP

 Table 1.1. Product Selection Guide





Figure 1.2. C8051F001/06/11/16 Block Diagram



1.8. Comparators and DACs

The C8051F000 MCU Family has two 12-bit DACs and two comparators on chip (the second comparator, CP1, is not bonded out on the F002, F007, F012, and F017). The MCU data and control interface to each comparator and DAC is via the Special Function Registers. The MCU can place any DAC or comparator in low power shutdown mode.

The comparators have software programmable hysteresis. Each comparator can generate an interrupt on its rising edge, falling edge, or both. The comparators' output state can also be polled in software. These interrupts are capable of waking up the MCU from idle mode. The comparator outputs can be programmed to appear on the Port I/O pins via the Crossbar.

The DACs are voltage output mode and use the same voltage reference as the ADC. They are especially useful as references for the comparators or offsets for the differential inputs of the ADC.



Figure 1.11. Comparator and DAC Diagram





Figure 5.4. AMX0CF: AMUX Configuration Register (C8051F00x)

R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
-	-	-	-	AIN67IC	AIN45IC	AIN23IC	AIN01IC	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xBA
Bits7-4	UNUSED. Rea	d = 0000b; V	Vrite = don't	care				
Bit3:	AIN67IC: AIN6	5. AIN7 Inpu	t Pair Config	uration Bit				
	0: AIN6 and A	N7 are inder	pendent singl	ed-ended inn	uts			
	$1 \cdot AIN6 AIN7$	are (respecti	velv) + - dif	ferential inpu	ut pair			
Bit2.	AIN45IC · AIN4	L AIN5 Inpu	t Pair Config	uration Bit	n puii			
D1(2)	0 AIN4 and Al	N5 are inder	endent singl	ed-ended inn	uts			
	1. Λ IN/4 Λ IN/5	are (respecti	$v_{alv} \perp dif$	forential input	uto it pair			
Dit1.	AIN22IC: AIN2	AIN3 Inpu	t Dair Config	uration Bit	n pan			
DITI.	AIN25IC. AIN2	N2 are inder	t Fail Coiling	ad and ad inn	uto			
	$\begin{array}{c} 0. \text{AIN2} \text{allu} \text{AIN2} \\ 1. \text{AIN2} \text{AIN2} \end{array}$	and (machine)	volu) - dif	formatical input	uis			
D:40	1: AIN2, AIN3	are (respecti	very) +, - dil	ierential inpl	it pair			
B1t0:	AINUTIC: AINU), AINT Inpu	t Pair Config	uration Bit				
	0: AINO and A	INI are indep	pendent singl	ed-ended inp	uts			
	1: AIN0, AIN1	are (respecti	vely) +, - dif	ferential inpu	it pair			
NOTE.	The ADC Date V	Word is in 2'		t format for	honnala oon	figured og dif	Formatio	
NOTE:	The ADC Data	word is in 2	s complemen	it format for (channels con	ingured as dif	Terential.	



D 711	5.00	5.00	D (11)	5 411	5.00	D 111		5
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
ADCSC2	ADCSC1	ADCSC0	-	-	AMPGN2	AMPGN1	AMPGN0	01100000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xBC
Bits7-5: AI	DCSC2-0: AE	DC SAR Con	version Cloc	k Period Bits				
00	0: SAR Conv	version Clock	x = 1 System	Clock				
00	1: SAR Conv	version Clock	x = 2 System	Clocks				
01	0: SAR Conv	version Clock	x = 4 System	Clocks				
01	1: SAR Conv	version Clock	x = 8 System	Clocks				
1x	x: SAR Conv	version Clock	x = 16 System	ns Clocks				
(N	ote: the SAR	Conversion (Clock should	be < 2MHz)			
Bits4-3: UN	JUSED. Rea	d = 00b: Wri	te = don't ca	re	/			
Bits2-0: AN	$\frac{1000}{100}$	DC Internal A	Amplifier Ga	in				
00	0: Gain = 1		impilier Gu					
00	1: $Gain = 2$							
01	0: Gain = 4							
01	1: $Gain = 8$							
10:	x: Gain = 16							
11	x: Gain $= 0.5$	5						
		•						

Figure 5.6. ADC0CF: ADC Configuration Register (C8051F00x)



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_		Tigui C 5.			ata moru	MDD Reg		JII UUA)	
	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value
									00000000
	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
									0xBF
									0.121
		C Data Wor	d Dita						
	DIIS/-0. AL	C Data Wor	u Dits						
	Fo	r ADLJST =	1: Upper 8-b	its of the 12-	bit ADC Dat	a Word.			
	Fo	r ADI IST –	0. Bits7-4 an	e the sign ext	ension of Bit	3 Bits 3-0 :	are the unner	4-bits of the	
	10		0. Dits/ $+$ div	e the sign ext	clision of Di	5. Dits 5.00	are the upper	+ bits of the	
	12	-bit ADC Dat	ta Word.						

Figure 5.8. ADC0H: ADC Data Word MSB Register (C8051F00x)







6. ADC (10-Bit, C8051F010/1/2/5/6/7 Only)

The ADC subsystem for the C8051F010/1/2/5/6/7 consists of a 9-channel, configurable analog multiplexer (AMUX), a programmable gain amplifier (PGA), and a 100ksps, 10-bit successive-approximation-register ADC with integrated track-and-hold and programmable window detector (see block diagram in Figure 6.1). The AMUX, PGA, Data Conversion Modes, and Window Detector are all configurable under software control via the Special Function Register's shown in Figure 6.1. The ADC subsystem (ADC, track-and-hold and PGA) is enabled only when the ADCEN bit in the ADC Control register (ADC0CN, Figure 6.7) is set to 1. The ADC subsystem is in low power shutdown when this bit is 0. The Bias Enable bit (BIASE) in the REF0CN register (see Figure 9.2) must be set to 1 in order to supply bias to the ADC.





6.1. Analog Multiplexer and PGA

Eight of the AMUX channels are available for external measurements while the ninth channel is internally connected to an on-board temperature sensor (temperature transfer function is shown in Figure 6.3). Note that the PGA gain is applied to the temperature sensor reading. AMUX input pairs can be programmed to operate in either the differential or single-ended mode. This allows the user to select the best measurement technique for each input channel, and even accommodates mode changes "on-the-fly". The AMUX defaults to all single-ended inputs upon reset. There are two registers associated with the AMUX: the Channel Selection register AMX0SL (Figure 6.5), and the Configuration register AMX0CF (Figure 6.4). The table in Figure 6.5 shows AMUX functionality by channel for each possible configuration. The PGA amplifies the AMUX output signal by an amount determined by the AMPGN2-0 bits in the ADC Configuration register, ADC0CF (Figure 6.6). The PGA can be software-programmed for gains of 0.5, 1, 2, 4, 8 or 16. It defaults to unity gain on reset.



8. COMPARATORS

The MCU family has two on-chip analog voltage comparators as shown in Figure 8.1. The inputs of each Comparator are available at the package pins. The output of each comparator is optionally available at the package pins via the I/O crossbar (see Section 15.1). When assigned to package pins, each comparator output can be programmed to operate in open drain or push-pull modes (see section 15.3).

The hysteresis of each comparator is software-programmable via its respective Comparator control register (CPT0CN, CPT1CN). The user can program both the amount of hysteresis voltage (referred to the input voltage) and the positive and negative-going symmetry of this hysteresis around the threshold voltage. The output of the comparator can be polled in software, or can be used as an interrupt source. Each comparator can be individually enabled or disabled (shutdown). When disabled, the comparator output (if assigned to a Port I/O pin via the Crossbar) defaults to the logic low state, its interrupt capability is suspended and its supply current falls to less than 1μ A. Comparator 0 inputs can be externally driven from -0.25V to (AV+) + 0.25V without damage or upset.

The Comparator 0 hysteresis is programmed using bits 3-0 in the Comparator 0 Control Register CPT0CN (shown in Figure 8.3). The amount of *negative* hysteresis voltage is determined by the settings of the CP0HYN bits. As shown in Figure 8.2, settings of 10, 4 or 2mV of negative hysteresis can be programmed, or negative hysteresis can be disabled. In a similar way, the amount of *positive* hysteresis is determined by the setting the CP0HYP bits.

Comparator interrupts can be generated on both rising-edge and falling-edge output transitions. (For Interrupt enable and priority control, see Section 10.4). The CPOFIF flag is set upon a Comparator 0 falling-edge interrupt, and the CPORIF flag is set upon the Comparator 0 rising-edge interrupt. Once set, these bits remain set until cleared by the CPU. The Output State of Comparator 0 can be obtained at any time by reading the CPOOUT bit. Note the comparator output and interrupt should be ignored until the comparator settles after power-up. Comparator 0 is enabled by setting the CPOEN bit, and is disabled by clearing this bit. Note there is a 20usec settling time for the comparator output to stabilize after setting the CPOEN bit or a power-up. Comparator 0 can also be programmed as a reset source. For details, see Section 13.

The operation of Comparator 1 is identical to that of Comparator 0, except the Comparator 1 is controlled by the CPT1CN Register (Figure 8.4). Comparator 1 can not be programmed as a reset source. Also, the input pins for Comparator 1 are not pinned out on the F002, F007, F012, or F017 devices. The complete electrical specifications for the Comparators are given in Table 8.1.



Figure 8.1. Comparator Functional Block Diagram



Table 8.1. Comparator Electrical Characteristics

VDD = 3.0V, AV + = 3.0V, $-40^{\circ}C$ to $+85^{\circ}C$ unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Response Time1	(CP+) - (CP-) = 100mV (Note 1)		4		μs
Response Time2	(CP+) - (CP-) = 10mV (Note 1)		12		μs
Common Mode Rejection			1.5	4	mV/V
Ratio					
Positive Hysteresis1	CPnHYP1-0 = 00		0	1	mV
Positive Hysteresis2	CPnHYP1-0 = 01	2	4.5	7	mV
Positive Hysteresis3	CPnHYP1-0 = 10	4	9	13	mV
Positive Hysteresis4	CPnHYP1-0 = 11	10	17	25	mV
Negative Hysteresis1	CPnHYN1-0 = 00		0	1	mV
Negative Hysteresis2	CPnHYN1-0 = 01	2	4.5	7	mV
Negative Hysteresis3	CPnHYN1-0 = 10	4	9	13	mV
Negative Hysteresis4	CPnHYN1-0 = 11	10	17	25	mV
Inverting or Non-inverting		-0.25		(AV+)	V
Input Voltage Range				+ 0.25	
Input Capacitance			7		pF
Input Bias Current		-5	0.001	+5	nA
Input Offset Voltage		-10		+10	mV
POWER SUPPLY					
Power-up Time	CPnEN from 0 to 1		20		μs
Power Supply Rejection			0.1	1	mV/V
Supply Current	Operating Mode (each comparator) at DC		1.5	10	μA

Note 1: CPnHYP1-0 = CPnHYN1-0 = 00.



Address	Register	Description	Page No.
0x89	TMOD	Counter/Timer Mode	143
0x91	TMR3CN	Timer 3 Control	152
0x95	TMR3H	Timer 3 High	153
0x94	TMR3L	Timer 3 Low	153
0x93	TMR3RLH	Timer 3 Reload High	153
0x92	TMR3RLL	Timer 3 Reload Low	153
0xFF	WDTCN	Watchdog Timer Control	96
0xE1	XBR0	Port I/O Crossbar Configuration 1	105
0xE2	XBR1	Port I/O Crossbar Configuration 2	107
0xE3	XBR2	Port I/O Crossbar Configuration 3	108
0x84-86, 0 0xA1-A3, 0xAE, 0xE 0xBD, 0xC 0xDF, 0xF	x96-97, 0x9C, 0xA9-AC, 33-B5, 0xB9, C9, 0xCE, 24-E5, 0xF1-F5	Reserved	

* Refers to a register in the C8051F000/1/2/5/6/7 only. ** Refers to a register in the C8051F010/1/2/5/6/7 only. *** Refers to a register in the C8051F005/06/07/15/16/17 only.



12. EXTERNAL RAM (C8051F005/06/07/15/16/17)

The C8051F005/06/07/15/16/17 MCUs include 2048 bytes of RAM mapped into the external data memory space. All of these address locations may be accessed using the external move instruction (MOVX) and the data pointer (DPTR), or using MOVX indirect addressing mode. If the MOVX instruction is used with an 8-bit address operand (such as @R1), then the high byte of the 16-bit address is provided by the External Memory Interface Control Register (EMI0CN as shown in Figure 12.1). Note: the MOVX instruction is also used for writes to the Flash memory. See Section 11 for details. The MOVX instruction accesses XRAM by default (i.e. PSTCL.0 = 0).

For any of the addressing modes the upper 5-bits of the 16-bit external data memory address word are "don't cares". As a result, the 2048-byte RAM is mapped modulo style over the entire 64k external data memory address range. For example, the XRAM byte at address 0x0000 is also at address 0x0800, 0x1000, 0x1800, 0x2000, etc. This is a useful feature when doing a linear memory fill, as the address pointer doesn't have to be reset when reaching the RAM block boundary.

R	R	R	R	R	R/W	R/W	R/W	Reset Value
-	-	-	-	-	PGSEL2	PGSEL1	PGSEL0	00000000
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:
								0xAF
		1 000001						
Bits 7-3:1	Not Used – rea	ads 00000b						
Bits 2-0:1	PGSEL[2:0]: 2	XRAM Page	Select Bits					
	The XRAM Pa	age Select Bi	its provide th	e high byte o	f the 16-bit e	xternal data i	memory	
8	address when	using an 8-bi	it MOVX cor	mmand, effec	tively selecti	ng a 256-byt	e page of	
]	RAM. The up	per 5-bits ar	e "don't care	s", so the 2k	address block	ks are repeate	ed modulo	
(over the entire	64k externa	l data memor	y address spa	ace.			
(000: xxxxx000	Ob		-				
(001: xxxxx00	1b						
()10: xxxxx010	Ob						
(011: xxxxx01	1b						
1	100: xxxxx100	0b						
1	101: xxxxx10	1b						
1	110: xxxxx110	Ob						
1	111: xxxxx11	1b						

Figure 12.1. EMI0CN: External Memory Interface Control



-40°C to +85°C unless otherw	vise specified.				
PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
/RST Output Low Voltage	$I_{OL} = 8.5 \text{mA}, \text{VDD} = 2.7 \text{ to } 3.6 \text{V}$			0.6	V
/RST Input High Voltage		0.7 x			V
		VDD			
/RST Input Low Voltage				0.3 x	V
				VDD	
/RST Input Leakage Current	/RST = 0.0V		20		μΑ
VDD for /RST Output Valid		1.0			V
AV+ for /RST Output Valid		1.0			V
VDD POR Threshold (V _{RST})		2.40	2.55	2.70	V
Reset Time Delay	/RST rising edge after crossing reset	80	100	120	ms
	threshold				
Missing Clock Detector	Time from last system clock to reset	100	220	500	μs
Timeout	generation				

Table 13.1. Reset Electrical Characteristics



Figure 14.3.	OSCXCN:	External	Oscillator	Control	Register
	0.0 0 0		0.0000000		

R	R/	W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value	
XTLVLD) XOSC	CMD2	XOSCMD1	XOSCMD0	-	XFCN2	XFCN1	XFCN0	00110000	
Bit7	Bi	t6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:	
									0xB1	
Bit7: X	XTLVLD	: Crys	tal Oscillator	Valid Flag						
(Valid on	ly who	en XOSCMI	$\mathbf{O} = 1\mathbf{x}\mathbf{x}.\mathbf{O}$						
C): Crysta	l Oscil	lator is unuse	ed or not ye	t stable					
1	l: Crysta	l Oscil	lator is runni	ng and stab	le (should rea	d 1ms after	Crystal Oscilla	ator is		
	enable	d to av	void transient	condition).						
Bits6-4: X	XOSCMI	D2-0: H	External Osci	llator Mode	Bits					
C	00x: Off.	XTA	L1 pin is gro	unded inter	nally.					
0	010: Syst	em Cl	ock from Ext	ernal CMO	S Clock on X	TAL1 pin.				
0	011: Syst	em Cl	ock from Ext	ernal CMO	S Clock on X	TAL1 pin d	ivided by 2.			
1	l0x: RC/	C Osc	illator Mode	with divide	by 2 stage.					
1	10: Crys	stal Os	cillator Mod	e 						
D:42	III: Crys	stal Os	cillator Mod	e with divid	e by 2 stage.					
Bito? 0. N	XESERV	ED. R	ead = undefi	ned, Write	= don't care					
Bits2-0: 2	XFCN2-0	: Exte	rnal Oscillato	or Frequenc	y Control Bits	5				
U		see ta	Die Delow							
Г	VECN	Crave	tol (VOSCM	D	PC (VOSCI)	$(D - 10_{\rm w})$	C (VOSCM	$D = 10_{\rm W}$		
	AFCN	(11v)		D –	KC (AOSCIM	D = 10x	C (AOSCIMI	D = 10X		
-	000	f < 1	2.51/17		f < 25kH7		K Factor – 0	14		
_	000	$1 \ge 1$ 12.51	2.3 MIZ	21.11.7	$1 \leq 23 \text{KHZ}$	501.11.7	K Factor = 1	4		
F	010	12.3	$\frac{KHZ}{S} = \frac{1}{2} \frac{S}{S}$		23 kHz $< 1 \leq$	1001-11-	K Factor = 4	.4		
-	010	30.3	5 KHZ $< 1 \le 9$	3.8KHZ	50 kHz $< 1 \le$		K Factor = 4	2		
-	100	93.8	$kHz < f \le 26$	/KHZ	$100 \text{ kHz} < f \le$	200kHz	K Factor = 1	3		
_	100	267k	$Hz < f \le 72$	2kHz	$200 \text{kHz} < f \le$	400kHz	K Factor = 3	8		
_	101	722k	$Hz < f \le 2.2$	3MHz	$400 \text{kHz} < \text{f} \le$	800kHz	K Factor = 1	00		
_	110	2.23	$MHz < f \le 6$.74MHz	$800 \text{kHz} < \text{f} \le$	1.6MHz	K Factor $= 4$	-20		
	111	f > 6	.74MHz		$1.6 MHz < f \le$	3.2MHz	K Factor $= 1$	400		
CRYSTA	L MOD	E (Cir	cuit from Fig	ure 14.1, O	ption 1; XOS	CMD = 11x)			
(Choose X	FCN v	value to mate	h the crysta	l or ceramic r	esonator fre	quency.			
DOMOD			T : 444	o o		10.)				
RC MOD	DE (Circu	it from	n Figure 14.1	, Option 2;	XOSCMD =	10x)				
(Choose os	Scillati	on frequency	range when	re:					
I	= 1.23(1	U ²) / (² U	$\mathbf{K} * \mathbf{C}$, wher	e . MII-						
I	= freque	ncy of	oscillation in	1 MHZ						
	C = capacitor value in pF									
ŀ	$\mathbf{x} = \mathbf{Pull} \cdot \mathbf{u}$	ip resi	stor value in	KQ						
	(C:	from		Intion 2. W	05010 1/)w)				
CMODE	Circuit	Foots	rigure 14.1, (\mathbf{KE}) for t^{1}	opuon 3; X	OSCIVID = I(JX) siradi				
۲ ۲	$\frac{10080 \text{ K}}{10080 \text{ K}}$	$\Gamma a C $	$I(\mathbf{K}\mathbf{\Gamma}) IOF IO(\mathbf{V})$	e oscination	inequency de	siled.				
L L	$= \mathbf{N}\mathbf{\Gamma} / ($ $= \mathbf{f}\mathbf{r}_{0}$	$\mathbf{U}^{\mathrm{T}}\mathbf{A}$	v+), where	› M比?						
I	= neque	itor ve	USCIIIATION II		ning in nE					
	$\Delta V_{\perp} = \alpha_{1}$	nor va nalog l	Dower Supply	$\mathbf{J}_{1}, \mathbf{\Lambda}_{1} \mathbf{A} \mathbf{L}_{2}$	pills III pr n volts					
F	$\mathbf{v} + - \mathbf{A}$	liaiog I	ower supply							



not affect the push-pull Port I/O. Furthermore, the weak pullup is turned off on an open-drain output that is driving a 0 to avoid unnecessary power dissipation.

The third and final step is to initialize the individual resources selected using the appropriate setup registers. Initialization procedures for the various digital resources may be found in the detailed explanation of each available function. The reset state of each register is shown in the figures that describe each individual register.





Figure 15.2. Port I/O Cell Block Diagram





R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value				
WEAKPUD	XBARE	-	-	-	-	-	CNVSTE	00000000				
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:				
Bit7:	WEAKPUD: I	Port I/O Wea	k Pull-up Di	sable Bit								
(0: Weak Pull-	ups Enabled	(except for l	Ports whose I	/O are config	gured as push	-pull)					
	1: Weak Pull-	ups Disabled	1		e		1 /					
Bit6:	XBARE: Cros	sbar Enable	Bit									
(0: Crossbar D	isabled										
	1: Crossbar E	nabled										
Bits5-1:	UNUSED. Re	ead = 00000t	, Write $=$ do	n't care.								
Bit0:	CNVSTE: AD	C Convert S	tart Input En	able Bit								
(0: CNVSTR u	inavailable a	t Port pin.									
	1: CNVSTR r	outed to Por	t Pin.									
Example	Usage of XBI	<u>R0, XBR1, X</u>	BR2:									
When sel	lected, the dig	ital resource	s fill the Po	rt I/O pins in	order (top t	to bottom as	shown in					
Table 15	.1) starting w	vith P0.0 thr	ough P0.7,	and then P1	.0 through I	P1.7, and fin	ally P2.0					
through I	P2.7. If the di	igital resourc	es are not m	apped to the	Port I/O pin	s, they defau	lt to their					
matching	internal Port	Register bits.										
Example	Example1: If $XBR0 = 0x11$, $XBR1 = 0x00$, and $XBR2 = 0x40$:											
P0.0=SD	A, P0.1=SCL,	P0.2=CEX0	, P0.3=CEX	1, P0.4 P2	.7 map to co	rresponding l	Port I/O.					
Example2	2: If XBR0 = 0	0x80, XBR1	= 0x04, and	XBR2 = 0x4	1:							
P0.0=CP0	0, P0.1=/INT0	$P_{0}, P_{0}.2 = CN^{2}$	VSTR, P0.3	P2.7 map	to correspond	ding Port I/O	•					

Figure 15.5. XBR2: Port I/O CrossBar Register 2



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value			
P3.7	P3.6	P3.5	P3.4	P3.3	P3.2	P3.1	P3.0	11111111			
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:			
							(bit addressable)	0xB0			
Bits7-0:	P3.[7:0]										
	(Write)										
	0: Logic Low Output.										
	1: Logic High	n Output (hig	h-impedance	if correspond	ding PRT3C	F.n bit = 0					
	(Read)	1 \ 0	1	1	U	,					
	0: P3 n is logic low										
1. P3 n is logic high											
	1. 1.5.11 15 10g	ie ingin									

Figure 15.13. P3: Port3 Register





Table 15.2. Port I/O DC Electrical Characteristics

VDD = 2.7 to 3.6V, -40°C to +85°C unless otherwise specified.

PARAMETER	CONDITIONS	MIN	ТҮР	MAX	UNITS
Output High Voltage	$I_{OH} = -10uA$, Port I/O push-pull	VDD –			V
		0.1			
	$I_{OH} = -3mA$, Port I/O push-pull	VDD –			
		0.7			
	I _{OH} = -10mA, Port I/O push-pull		VDD –		
			0.8		
Output Low Voltage	$I_{OL} = 10uA$			0.1	V
	$I_{OL} = 8.5 \text{mA}$			0.6	
	$I_{OL} = 25 \text{mA}$		1.0		
Input High Voltage		0.7 x			V
		VDD			
Input Low Voltage				0.3 x	V
				VDD	
Input Leakage Current	DGND < Port Pin < VDD, Pin Tri-state				μA
	Weak Pull-up Off			±1	·
	Weak Pull-up On		30		
Capacitive Loading			5		pF



Figure 16.4	. SMB0CN:	SMBus	Control	Register
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R	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
BUSY	ENSMB	STA	STO	SI	AA	FTE	TOE	00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:		
							(bit addressable)	0xC0		
Bit7:	BUSY: Busy S	Status Flag.								
	0: SMBus is fr	ee								
	1: SMBus is b	usv								
Bit6:	ENSMB: SME	Bus Enable.								
	This bit enable	es/disables th	e SMBus ser	ial interface.						
	0: SMBus disabled.									
	1: SMBus enal	bled.								
Bit5:	STA: SMBus	Start Flag.								
	0: No START	condition is	transmitted.							
	1: When opera	ting as a ma	ster, a STAR	T condition i	s transmitted	if the bus is	free. (If the			
	bus is not free.	, the START	is transmitte	d after a STO	OP is received	1.) If STA is	set after one			
	or more bytes	have been tra	ansmitted or	received and	before a STC	OP is receive	d, a repeated			
	START condit	tion is transn	nitted. STO	should be ext	olicitly cleare	d before sett	ing STA to			
	logic 1.			1	5		0			
Bit4:	STO: SMBus	Stop Flag.								
	0: No STOP c	ondition is tr	ansmitted.							
	1: Setting STC) to logic 1 c	auses a STO	P condition to	be transmitt	ed. When a	STOP			
	condition is re	ceived. hard	ware clears S	TO to logic (). If both ST	A and STO a	re set. a			
	STOP condition	on is transmit	ted followed	by a STAR	condition.	In slave mod	e. setting the			
	STO flag caus	es SMBus to	behave as if	a STOP con	dition was re	ceived.	.,			
Bit3:	SI: SMBus Se	rial Interrupt	Flag.							
	This bit is set l	by hardware	when one of	27 possible \$	SMBus states	is entered.	Status code			
	0xF8 does not	cause SI to l	be set.) Whe	n the SI inter	rupt is enable	ed, setting thi	s bit causes			
	the CPU to ve	ctor to the SI	ABus interru	pt service rou	tine. This bi	it is not autor	natically			
	cleared by har	dware and m	ust be cleare	d by software	2.		5			
Bit2:	AA: SMBus A	ssert Ackno	wledge Flag.	2						
	This bit define	s the type of	acknowledg	e returned du	ring the ackn	owledge cyc	le on the			
	SCL line.	J			8					
	0: A "not ackn	owledge" (h	igh level on	SDA) is retur	ned during th	ne acknowled	lge cycle.			
	1: An "acknow	vledge" (low	level on SD.	A) is returned	l during the a	cknowledge	cycle.			
Bit1:	FTE: SMBus I	Free Timer E	nable Bit	,	U	e	5			
	0: No timeout	when SCL i	s high							
	1: Timeout wl	hen SCL hig	h time excee	ds limit speci	fied by the S	MB0CR valu	ie.			
Bit0:	TOE: SMBus	Timeout Ena	ble Bit	1	5					
	0: No timeout	when SCL i	s low.							
	1: Timeout when SCL low time exceeds limit specified by Timer 3, if enabled.									
					2					



Figure 17.2. Typical SPI Interconnection



17.1. Signal Descriptions

The four signals used by the SPI (MOSI, MISO, SCK, NSS) are described below.

17.1.1. Master Out, Slave In

The master-out, slave-in (MOSI) signal is an output from a master device and an input to slave devices. It is used to serially transfer data from the master to the slave. Data is transferred most-significant bit first.

17.1.2. Master In, Slave Out

The master-in, slave-out (MISO) signal is an output from a slave device and an input to the master device. It is used to serially transfer data from the slave to the master. Data is transferred most-significant bit first. A SPI slave places the MISO pin in a high-impedance state when the slave is not selected.

17.1.3. Serial Clock

The serial clock (SCK) signal is an output from the master device and an input to slave devices. It is used to synchronize the transfer of data between the master and slave on the MOSI and MISO lines.

17.1.4. Slave Select

The slave select (NSS) signal is an input used to select the SPI module when in slave mode by a master, or to disable the SPI module when in master mode. When in slave mode, it is pulled low to initiate a data transfer and remains low for the duration of the transfer.



R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	Reset Value		
SCR7	SCR6	SCR5	SCR4	SCR3	SCR2	SCR1	SCR0	00000000		
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0	SFR Address:		
								0x9D		
Bits7-0.	SCR7-SCR0	SPI Clock R	ate							
Dit37 0. 1	Those bits det	ormina tha fr	actionate of the	a SCK outpu	it when the S	DI modulo is				
-			equency of u	The SCK Output	it when the S		1			
G	configured for	master mod	e operation.	The SCK clo	ck frequency	is a divided	down			
, v	version of the	system clock	and is given	n in the follow	wing equation	ns:				
f	$f_{SCK} = 0.5 * f_{S}$	_{YSCLK} / (SPI0	CKR + 1),	for C	\leq SPI0CKF	$R \leq 255,$				

Figure 17.7. SPI0CKR: SPI Clock Rate Register







								Reset Value	
WRMD3	WRMD2	WRMD1	WRMD0	RDMD3	RDMD2	RDMD1	RDMD0	00000000	
Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0		
This register determines how the Flash interface logic will respond to reads and writes to the FLASHDAT Register.									
 Bits7-4: WRMD3-0: Write Mode Select Bits. The Write Mode Select Bits control how the interface logic responds to writes to the FLASHDAT Register per the following values: 0000: A FLASHDAT write replaces the data in the FLASHDAT register, but is otherwise ignored. 0001: A FLASHDAT write initiates a write of FLASHDAT into the memory location addressed by the FLASHADR register. FLASHADR is incremented by one when complete. 0010: A FLASHDAT write initiates an erasure (sets all bytes to 0xFF) of the Flash page containing the address in FLASHADR. FLASHDAT must be 0xA5 for the erase to occur. FLASHADR is not affected. If FLASHADR = 0x7DFE – 0x7DFF, the entire user space will be erased (i.e. entire Flash memory except for Reserved area 0x7E00 – 0x7FFF). 								2	
Bits3-0: I	RDMD3-0: Re The Read Moo FLASHDAT I 2000: A FLAS ignored 2001: A FLAS if no op 2010: A FLAS operatio FLASH without (All other value	ead Mode Se de Select Bits Register per t SHDAT read SHDAT read peration is cur SHDAT read on is active a IDAT. This i initiating an uses for RDM	lect Bits. s control how he following provides the initiates a re rrently active initiates a re nd any data f mode allows extra read. D3-0 are rese	y the interface values: e data in the F ad of the byt y. This mode ad of the byt rom a previo single bytes erved.)	E logic respon FASHDAT re e addressed b is used for b e addressed b us read has al to be read (or	nds to reads to gister, but is by the FLASI lock reads. by FLASHAI lready been r the last byte	o the otherwise HADR registe DR only if no read from e of a block)	21	

Figure 21.3. FLASHCON: JTAG Flash Control Register





